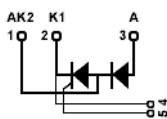


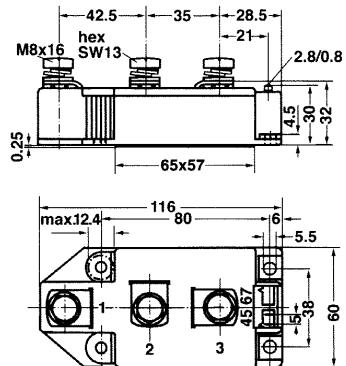
STD/SDT320

Thyristor-Diode Modules, Diode-Thyristor Modules



Type	V_{RSM} V_{DSM}	V_{RRM} V_{DRM}
	V	V
STD/SDT320GK08	900	800
STD/SDT320GK12	1300	1200
STD/SDT320GK14	1500	1400
STD/SDT320GK16	1700	1600
STD/SDT320GK18	1900	1800

Dimensions in mm (1mm=0.0394")



Symbol	Test Conditions	Maximum Ratings	Unit
I_{TRMS} , I_{FRMS} I_{TAVM} , I_{FAVM}	$T_{VJ}=T_{VJM}$ $T_c=85^\circ C$; 180° sine	500 320	A
I_{TSM} , I_{FSM}	$T_{VJ}=45^\circ C$ $V_R=0$	9200 9800	A
	$T_{VJ}=T_{VJM}$ $V_R=0$	8000 8600	
$\int i^2 dt$	$T_{VJ}=45^\circ C$ $V_R=0$	420000 400000	$A^2 s$
	$T_{VJ}=T_{VJM}$ $V_R=0$	320000 306000	
$(di/dt)_{cr}$	$T_{VJ}=T_{VJM}$ $f=50Hz$, $t_p=200\mu s$ $V_D=2/3V_{DRM}$ $I_G=1A$ $dI/dt=1A/\mu s$	100 500	$A/\mu s$
	repetitive, $I_T=960A$ non repetitive, $I_T=320A$		
$(dv/dt)_{cr}$	$T_{VJ}=T_{VJM}$; $V_{DR}=2/3V_{DRM}$ $R_{GK}=\infty$; method 1 (linear voltage rise)	1000	$V/\mu s$
P_{GM}	$T_{VJ}=T_{VJM}$ $I_T=I_{TAVM}$	120 60	W
P_{GAV}		20	W
V_{RGM}		10	V
T_{VJ} T_{VJM} T_{stg}		-40...+140 140 -40...+125	$^\circ C$
V_{ISOL}	50/60Hz, RMS $I_{ISOL}\leq 1mA$	3000 3600	V_\sim
M_d	Mounting torque (M5) Terminal connection torque (M8)	2.5-5/22-44 12-15/106-132	Nm/lb.in.
Weight	Typical including screws	320	g

STD/SDT320

Thyristor-Diode Modules, Diode-Thyristor Modules

Symbol	Test Conditions	Characteristic Values	Unit
I_{RRM}	$T_{VJ}=T_{VJM}$; $V_R=V_{RRM}$; $V_D=V_{DRM}$	70	mA
I_{DRM}		40	mA
V_T, V_F	$I_T, I_F=600A$; $T_{VJ}=25^\circ C$	1.32	V
V_{TO}	For power-loss calculations only ($T_{VJ}=140^\circ C$)	0.8	V
r_T		0.82	$m\Omega$
V_{GT}	$V_D=6V$; $T_{VJ}=25^\circ C$ $T_{VJ}=-40^\circ C$	2 3	V
I_{GT}	$V_D=6V$; $T_{VJ}=25^\circ C$ $T_{VJ}=-40^\circ C$	150 200	mA
V_{GD}	$T_{VJ}=T_{VJM}$; $V_D=2/3V_{DRM}$	0.25	V
I_{GD}		10	mA
I_L	$T_{VJ}=25^\circ C$; $t_p=30\mu s$; $V_D=6V$ $I_G=0.45A$; $dI/dt=0.45A/\mu s$	200	mA
I_H	$T_{VJ}=25^\circ C$; $V_D=6V$; $R_{GK}=\infty$	150	mA
t_{gd}	$T_{VJ}=25^\circ C$; $V_D=1/2V_{DRM}$ $I_G=1A$; $dI/dt=1A/\mu s$	2	us
t_q	$T_{VJ}=T_{VJM}$; $I_T=300A$; $t_p=200\mu s$; $-dI/dt=10A/\mu s$ $V_R=100V$; $dV/dt=50V/\mu s$; $V_D=2/3V_{DRM}$	typ. 200	us
Q_s	$T_{VJ}=125^\circ C$; $I_T, I_F=400A$; $-dI/dt=50A/\mu s$	760	uC
I_{RM}		275	A
R_{thJC}	per thyristor/diode; DC current per module	0.112 0.056	K/W
R_{thJK}	per thyristor/diode; DC current per module	0.152 0.076	K/W
ds	Creeping distance on surface	12.7	mm
da	Strike distance through air	9.6	mm
a	Maximum allowable acceleration	50	m/s^2

FEATURES

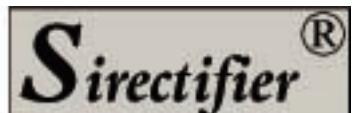
- * International standard package
- * Direct copper bonded Al₂O₃-ceramic base plate
- * Planar passivated chips
- * Isolation voltage 3600 V~

APPLICATIONS

- * Motor control
- * Power converter
- * Heat and temperature control for industrial furnaces and chemical processes
- * Lighting control
- * Contactless switches

ADVANTAGES

- * Space and weight savings
- * Simple mounting
- * Improved temperature and power cycling
- * Reduced protection circuits



STD/SDT320

Thyristor-Diode Modules, Diode-Thyristor Modules

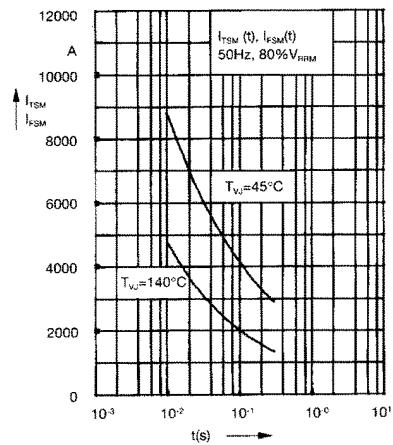


Fig. 1 Surge overload current
 I_{TSM} , I_{FSM} : Crest value, t: duration

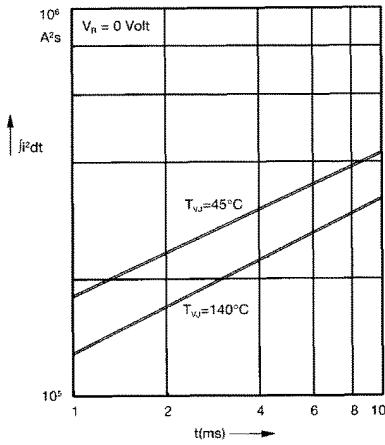


Fig. 2 $\int i^2 dt$ versus time (1-10 ms)

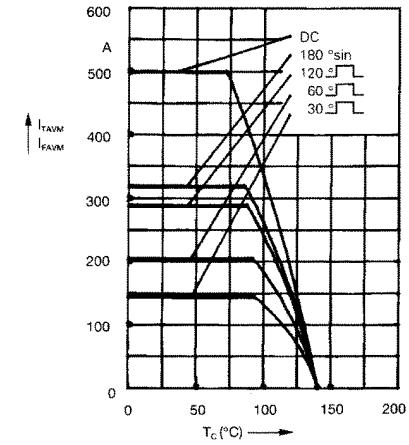


Fig. 2a Maximum forward current
at case temperature

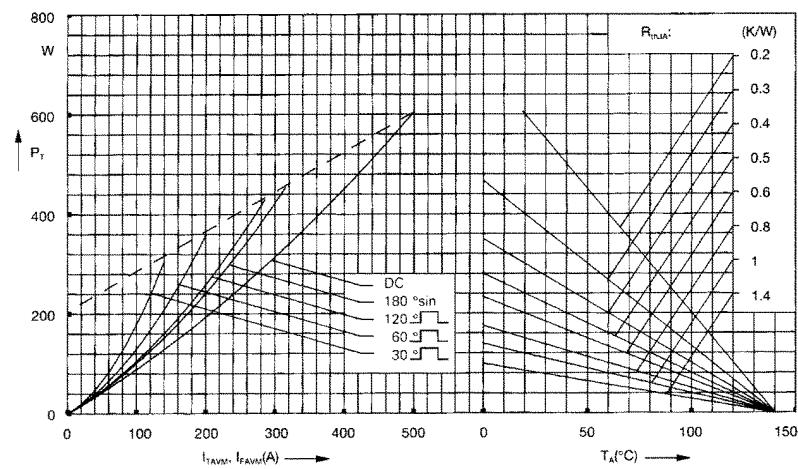


Fig. 3 Power dissipation versus on-state current and ambient temperature
(per thyristor or diode)

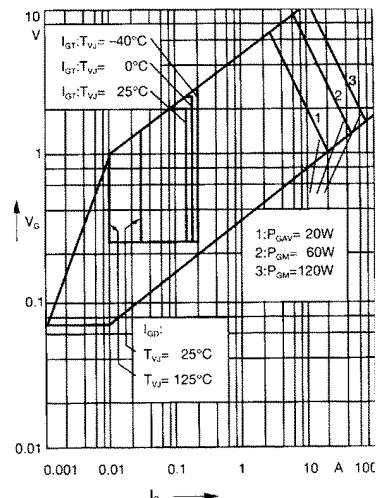


Fig. 4 Gate trigger characteristics

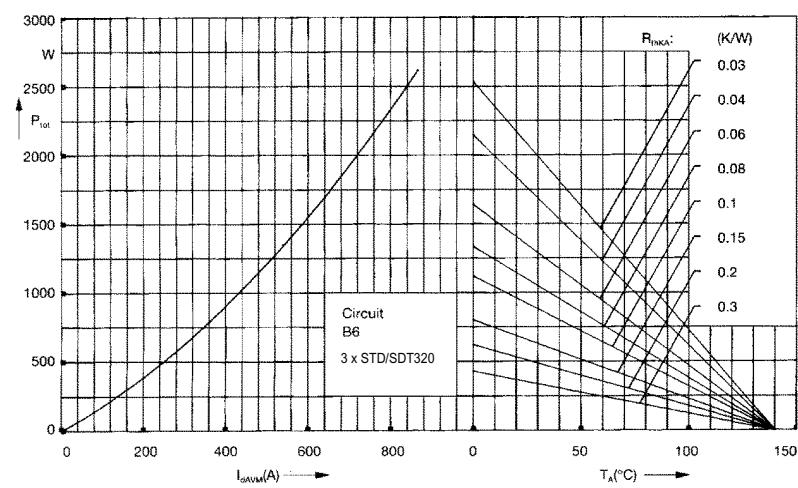


Fig. 5 Three phase rectifier bridge: Power dissipation versus direct output current
and ambient temperature

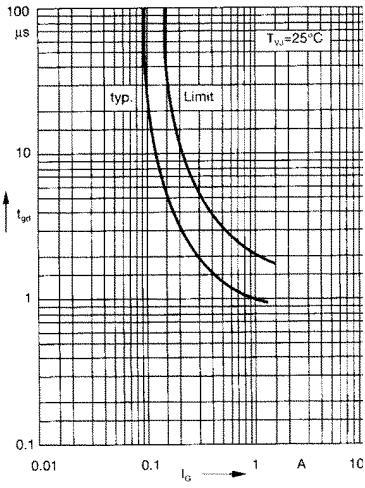


Fig. 6 Gate trigger delay time

STD/SDT320

Thyristor-Diode Modules, Diode-Thyristor Modules

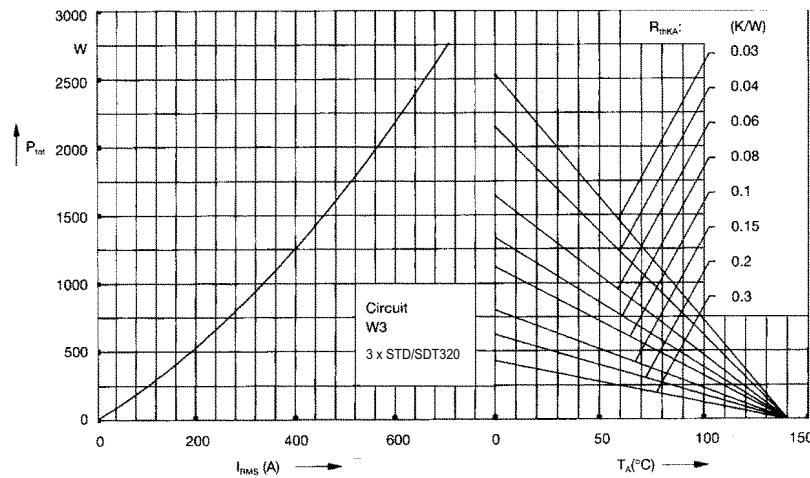


Fig. 7 Three phase AC-controller:
Power dissipation versus RMS
output current and ambient
temperature

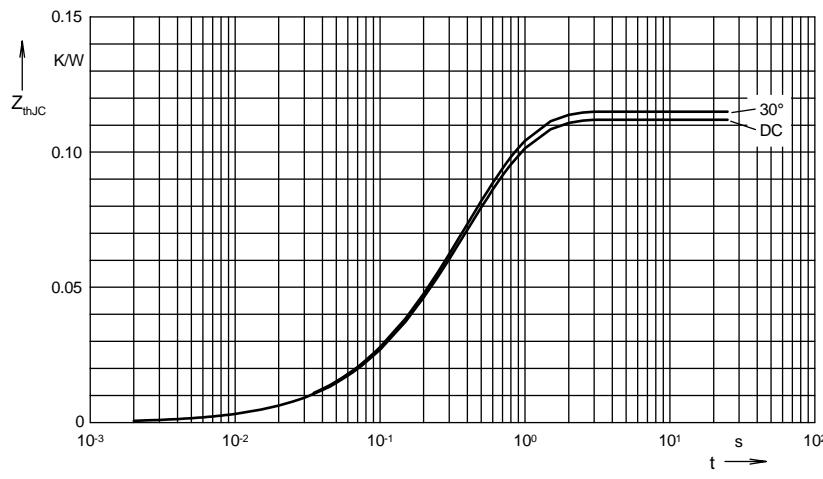


Fig. 8 Transient thermal impedance
junction to case (per thyristor or
diode)

R_{thJC} for various conduction angles d:

d	R_{thJC} (K/W)
DC	0.112
180°C	0.113
120°C	0.114
60°C	0.115
30°C	0.115

Constants for Z_{thJC} calculation:

i	R_{thi} (K/W)	t_i (s)
1	0.003	0.099
2	0.0143	0.168
3	0.0947	0.456

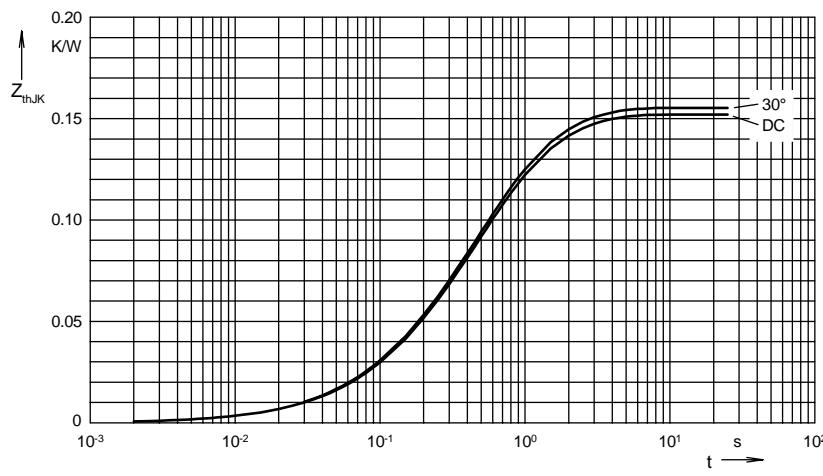


Fig. 9 Transient thermal impedance
junction to heatsink (per thyristor
or diode)

R_{thJK} for various conduction angles d:

d	R_{thJK} (K/W)
DC	0.152
180°C	0.154
120°C	0.154
60°C	0.155
30°C	0.155

Constants for Z_{thJK} calculation:

i	R_{thi} (K/W)	t_i (s)
1	0.003	0.099
2	0.0143	0.168
3	0.0947	0.456
4	0.04	1.36